



Product Change Notification

Change Notification #: 114808 - 00
Change Title: Intel® Hot-swap Drive Cage Kit
FUP8X25S3HSDK,
PCN 114808-00, Product Material,
Replacement of components under RoHS
exemptions
Date of Publication: August 9, 2016

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	Aug 25, 2016
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Hot-Swap Drive Cage Kit for P4000 Chassis Family FUP8X25S3HSDK:

1. Replacement of components containing substances listed under EU RoHS exemption 7(c). All new components are identical in form factor and function to the replaced ones.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FUP8X25S3HSDK	936425	H46616-002	H46616-003

PCN Revision History:

Date of Revision: August 9, 2016	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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